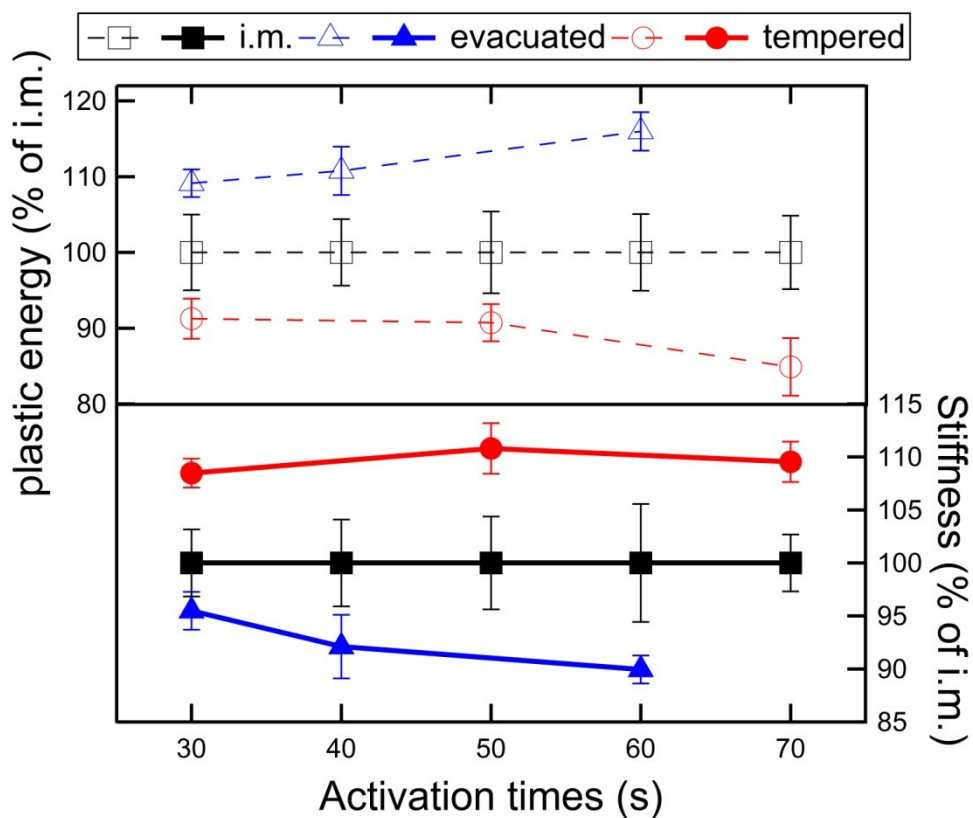


## Supporting Information

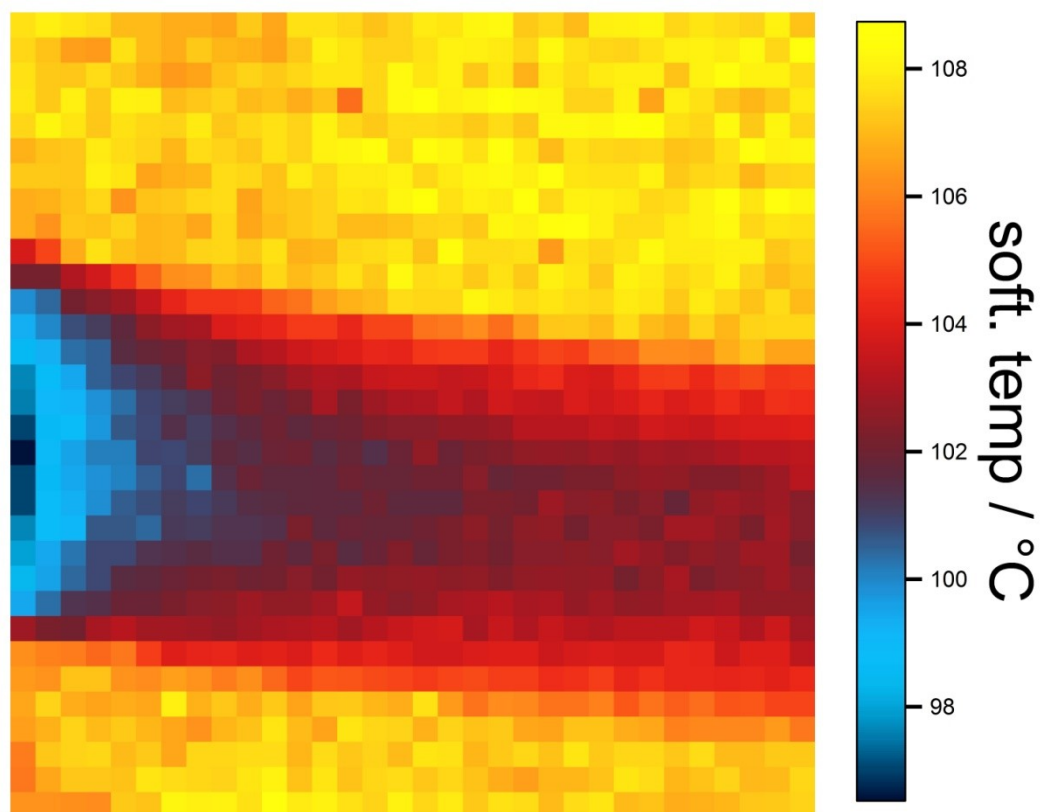
A detailed investigation of the solvent bonding process for  
microfluidic chip fabrication in micrometer scale<sup>†</sup>

Martin Laher\* and Sabine Hild

Institute of Polymer Science, Johannes Kepler University Linz, Altenberger  
Strasse 69, A-4040 Linz, Austria. E-mail: Martin.Laher@jku.at; Tel: +43  
732 2468 8711



**Fig. S1** Influence of post-activation treatments on plastic energy (dashed) and stiffness data (solid lines). Samples activated for a different time have either been evacuated at 0.8 mbar or isothermally tempered at 80°C for 1 h each. Percentage values are given relative to those measured on untreated, injected moulded chips (100 %).



**Fig. S2** A matrix of 32 x 32 measurement points provides higher resolution, but does suffer from the mutual influence of subsequent measurements. The matrix is acquired in vertical sections from left to right of the 20  $\mu\text{m}$  image.